



Senior Staff Engineer Failure Analysis

Job description

Perform IC (complex functional) Failure Analysis [FA] on wafer and package level from electrical verification, fault isolation and physical root cause analysis.

- Perform IC (complex functional) Failure Analysis [FA] on wafer and package level from electrical verification, fault isolation and physical root cause analysis.
- Prepare FA reports that can lead to root cause finding and corrective action to cross functional team.
- Participate, lead and present FA results in cross functional meetings, projects, yield improvement, urgent and important meetings.
- FA equipment / tool ownership.
- Interface with designers, test, product, process integration and unit process engineers, problem solving team, CQM team to understand the analysis requirement.
- Identify development opportunity of new EFA techniques and improvise FA skills and techniques to enhance analysis quality, speed and cost
- Responsible for achieving EFA KPIs.
- ATE test knowledge capability
- Setup of application board, product specific test methodology and localization capability.
- CAD navigation, layout and schematic analysis to identify the failure location and hypothesis
- Responsible for Fault Tree Analysis (FTA) in case of no physical defect found

Profile

- 6+ years working experience particularly related to FA field.

At a glance

Location: **Kulim (Malaysia)**
Job ID: **363199**
Start date: **Sep 01, 2022**
Entry level: **5+ years**
Type: **Full time**
Contract: **Permanent**

Apply to this position online by following the URL and entering the Job ID in our job search:

Job ID: **363199**
www.infineon.com/jobs



- Degree / Master / Ph D in Electrical and Electronic Engineering
- Knowledge in interpret a product datasheet.
- Have some experience in some of these field of knowledge: Complex Electrical Failure Verification and Localization, i.e. scan logic , Hi-Level Tester, SDL analysis, Sample preparation, i.e. mechanical polishing, precision cleaving, wet/dry chemical, backside preparation, package preparation. Imaging, i.e. optical, SEM and FIB (incl. Voltage Contrast). Repackaging skill i.e. COB, wire bonding, CAD Navigation plus Cross Mapping Schematic, Software Diagnosis on Logic FA Circuit troubleshooting via micro probing (A-pad, FIB pad or AFP) IC package Sample reconditioning, rework experience.

Benefits

- **Kulim:** Coaching, mentoring networking possibilities; Wide range of training offers & planning of career development; International assignments; Different career paths: Project Management, Technical Ladder, Management & Individual Contributor; Flexible working conditions; Holiday child care; Medical coverage; On-site social counselling and works doctor; Health promotion programs; On-site gym, jogging paths, beachvolleyball, tennis & soccer court; On-site canteen; Private insurance offers; Flexible transition into retirement

Why Us

Part of your life. Part of tomorrow.

Infineon is a world leader in semiconductor solutions that make life easier, safer, and greener. Our solutions for efficient energy management, smart mobility, and secure, seamless communications link the real and the digital world.

